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RF360 Europe GmbH

Data sheet

SAW RF downlink filter Base stations R-GSM

Series/type:	B5057
Ordering code:	B39941B5057U410
Date:	June 03, 2019
Version:	2.3

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1 Application

- Low-loss filter for Basestation R-GSM,transmit path (Tx)
- Usable pass band 39 MHz
- Unbalanced to unbalanced operation
- No matching required
- Filter impedance 50 Ω

2 Features

- Package code DCC6C
- Package size 3.0±0.1 mm × 3.0±0.1 mm
- Package height 1.1±0.125 mm
- Approximate weight 0.04 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Lead free soldering compatible with J-STD20C
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 1 (MSL1)

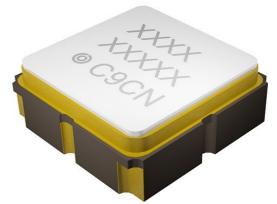
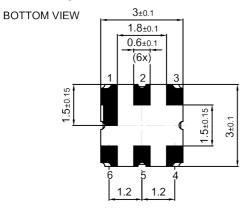


Figure 1: Picture of component with example of product marking.



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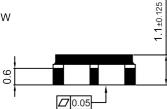
3 Package





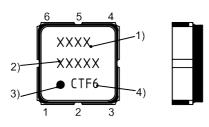
- 2 Input
- 5 Output
- 1, 3, 4, 6 Ground





TOP VIEW

SIDE VIEW



Device designation
 Last five digits of the lot number
 Marking for pad number 1
 Example of production location and date code

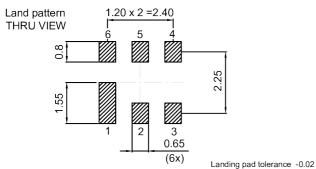


Figure 2: Drawing of package. See Sec. Package information (p. 18).



5 Matching circuit

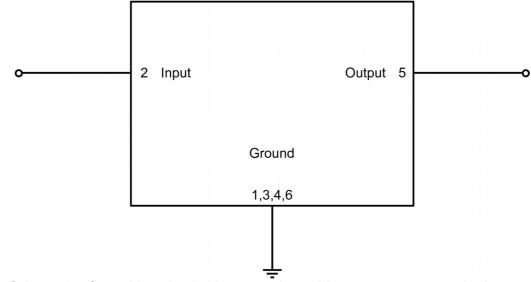


Figure 3: Schematic of matching circuit. No external matching components required.

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6 Characteristics

Temperature range for specification	T _{SPEC}	= −30 °C +80 °C
Input terminating impedance	Z	= 50 Ω
Output terminating impedance	Z _{OUT}	= 50 Ω

Characteristics				min. for T_{SPEC}	typ. @ +25 °C	max. for T _{SPEC}	
Center frequency			f _c	—	940.5		MHz
Maximum insertion attenuation			$\alpha_{_{max}}$				
	921 960	MHz		_	2.7	4.0 ¹⁾	dB
Amplitude ripple (p-p)			Δα				
	921 960	MHz		—	1.4	3.0 ²⁾	dB
Maximum VSWR			$VSWR_{_{max}}$				
@ input port	921 960	MHz		—	2.3	3.0 ³⁾	
@ output port	921 960	MHz		—	2.6	3.0 ³⁾	
Minimum attenuation			$\alpha_{_{min}}$				
	0.34) 800	MHz		25	47	—	dB
	800 880	MHz		26	39	—	dB
	880 905	MHz		20 ⁵⁾	31	—	dB
	905 915	MHz		2 ⁶⁾	6	—	dB
	980 985	MHz		23	42	—	dB
	985 1005	MHz		30	34	—	dB
	1005 1025	MHz		30	34		dB
	1025 1760	MHz		27	34		dB
	1760 2000	MHz		28	32	—	dB
	2000 4000	MHz		18	23	_	dB

¹⁾ 3.0 dB at 25°C.

²⁾ 2.0 dB at 25°C.

³⁾ 2.8 dB at 25°C.

⁴⁾ Final electrical test starts at 10 MHz.

⁵⁾ 28 dB at 25°C.

⁶⁾ 3 dB at 25°C.

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Temperature range for specification	$T_{_{\rm SPEC}}$	= −40 °C +85 °C
Input terminating impedance	Z _{IN}	= 50 Ω
Output terminating impedance	Z _{OUT}	= 50 Ω

Characteristics				min. for $T_{\rm SPEC}$	typ. @ +25 °C	max. for $T_{\rm SPEC}$	
Maximum insertion attenuation			α _{max}	SPEC		SPEC	
	921 960	MHz		_	2.7	4.5 ¹⁾	dB
Amplitude ripple (p-p)			Δα				
	921 960	MHz		_	1.4	3.2 ²⁾	dB
Maximum VSWR			VSWR _{max}				
@ input port	921 960	MHz		_	2.3	3.0 ³⁾	
@ output port	921 960	MHz		_	2.6	3.0 ³⁾	
Minimum attenuation			$\alpha_{_{min}}$				
	0.34) 800	MHz		25	47	—	dB
	800 880	MHz		26	39	_	dB
	880 905	MHz		20 ⁵⁾	31	_	dB
	905 915	MHz		2 ⁶⁾	6	_	dB
	980 985	MHz		23	42	_	dB
	985 1005	MHz		30	34	_	dB
	1005 1025	MHz		30	34	_	dB
	1025 1760	MHz		27	34	—	dB
	1760 2000	MHz		28	32	—	dB
	2000 4000	MHz		18	23	—	dB

¹⁾ 3.0 dB at 25°C.

²⁾ 2.0 dB at 25°C.

³⁾ 2.8 dB at 25°C.

⁴⁾ Final electrical test starts at 10 MHz.

⁵⁾ 28 dB at 25°C.

⁶⁾ 3 dB at 25°C.

7 **Maximum ratings**

Operable temperature	T _{op} = −40 °C +125 °C	
Storage temperature	<i>T</i> _{STG} ¹⁾ = −40 °C +125 °C	
DC voltage	V _{DC} = 5.0 V	
ESD voltage		
	$V_{\rm ESD}^{2)}$ = 125 V	Machine model.
	$V_{\rm ESD}^{3)} = 350 \rm V$	Human body model.
	$V_{\rm ESD}^{4)}$ = 1000 V	Charged device model.
Input power @ input port: 921 960 MHz	$P_{\rm IN} = 10 \rm dBm$	

1) Not valid for packaging material. Please refer to definition of Shelf life (p. 17).

2)

According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses. According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse. 3)

4) According to JESD22-C101C (CDM - Field Induced Charged Device Model), 3 negative & 3 positive pulses. Qualcomm RF360 Europe GmbH A Qualcomm – TDK Joint Venture

8 Transmission coefficient

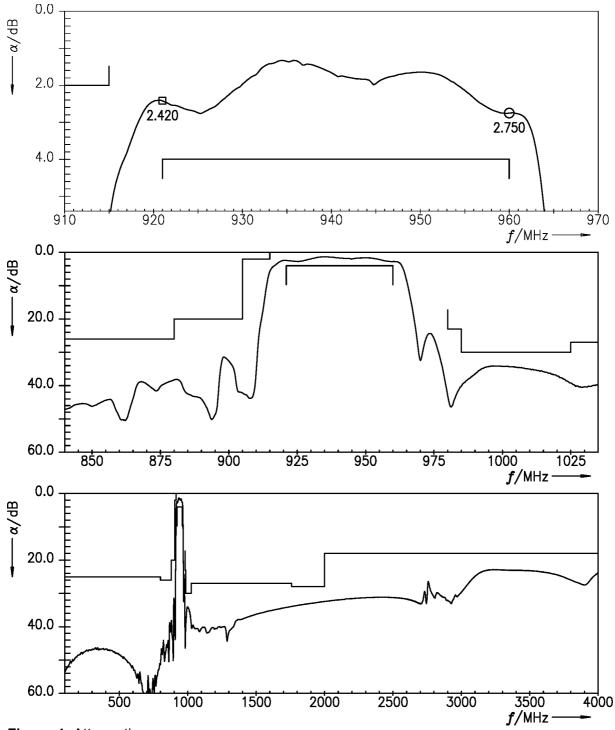


Figure 4: Attenuation.

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Z_{IN}=50 Ω

□ = 921.0 O = 960.0

9 **Reflection coefficients**

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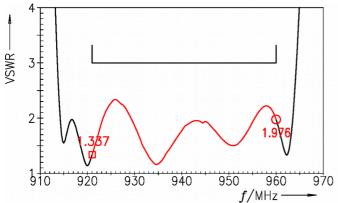


Figure 5: Reflection coefficient at input port.

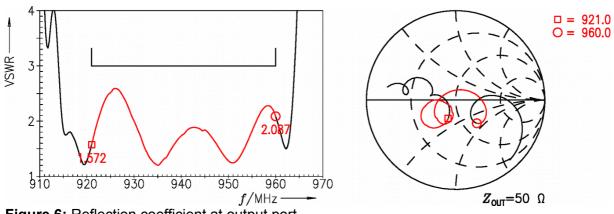
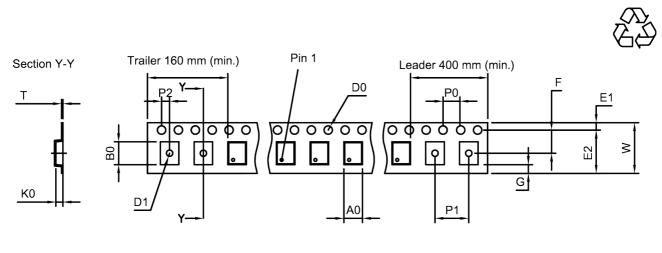


Figure 6: Reflection coefficient at output port.



10 Packing material

10.1 Tape



User direction of unreeling

Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

 $\begin{array}{c|c} A_0 & 3.25_{\pm 0.1} \text{ mm} \\ \hline B_0 & 3.3_{\pm 0.1} \text{ mm} \\ \hline D_0 & 1.5_{\pm 0.1/-0} \text{ mm} \\ \hline D_1 & 1.5 \text{ mm} (\text{min.}) \\ \hline E_1 & 1.75_{\pm 0.1} \text{ mm} \end{array}$

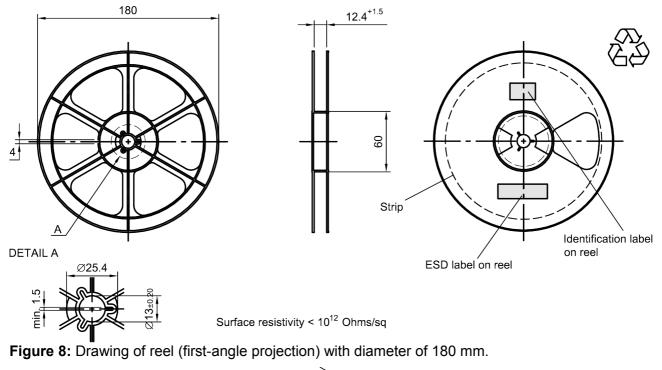
Table 1: Tape dimensions.

E2	10.25 mm (min.)
F	5.5±0.05 mm
G	0.75 mm (min.)
K ₀	1.5±0.1 mm
P ₀	4.0±0.1 mm

P ₁	4.0±0.1 mm
P_2	2.0±0.1 mm
Т	0.3±0.05 mm
W	12.0+0.3/-0.1 mm



10.2 Reel with diameter of 180 mm



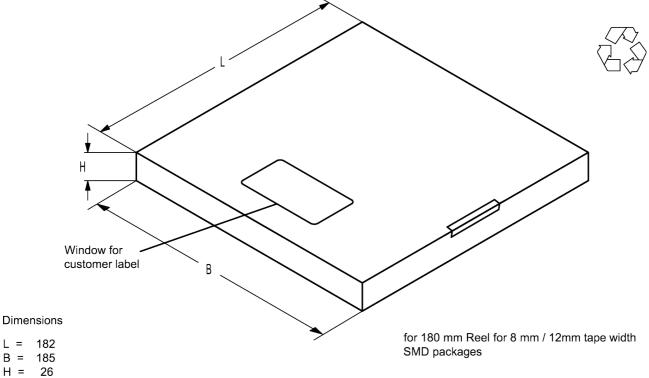


Figure 9: Drawing of folding box for reel with diameter of 180 mm.

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10.3 Reel with diameter of 330 mm

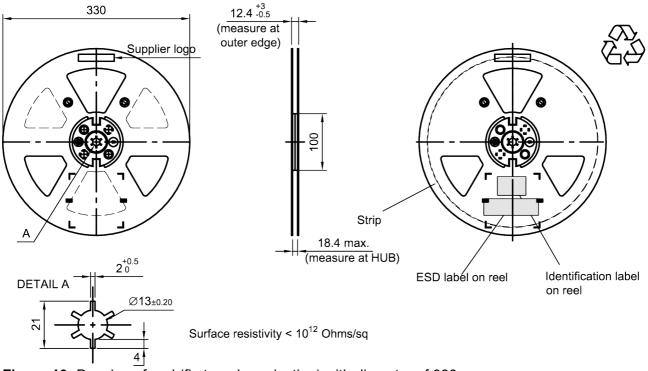


Figure 10: Drawing of reel (first-angle projection) with diameter of 330 mm.

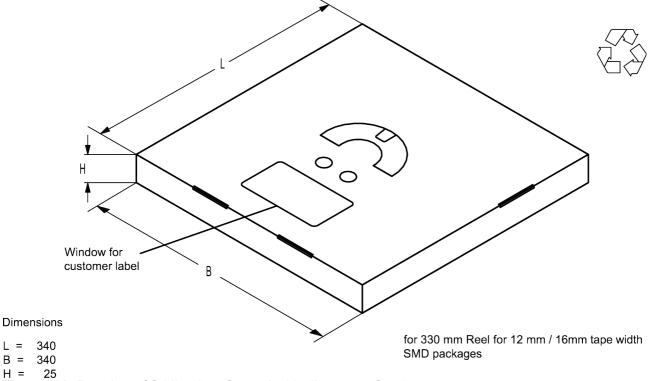


Figure 11: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with device designation, lot number, as well as production location and date code.

Device designation: The 4-character device designation of the ordering code is used for the marking.

Example for 4-character device designation: B3xxxxB1234xxxx

■ Lot number: The last 5 digits of the lot number are used for the marking.

Example: 12345

Production location and date code: The production location is Wuxi (encoded in the first character 'C'). The production date code is encoded in the last three characters according to Table 2.

1 st digit (day)					2 nd digit (year)			3 rd digit (month)					
Day	Code	Day	Code	Day	Code	Year	Code	Year	Code	Month	Code	Month	Code
1	1	11	А	21	М	2010	А	2022	Р	Jan	1	Jul	7
2	2	12	В	22	Ν	2011	В	2023	R	Feb	2	Aug	8
3	3	13	С	23	Р	2012	С	2024	S	Mar	3	Sep	9
4	4	14	D	24	R	2013	D	2025	Т	Apr	4	Oct	0
5	5	15	E	25	S	2014	Е	2026	U	May	5	Nov	N
6	6	16	F	26	Т	2015	F	2027	V	Jun	6	Dec	D
7	7	17	н	27	U	2016	Н	2028	W				
8	8	18	J	28	V	2017	J	2029	Х				
9	9	19	к	29	W	2018	К	2030	Z				
10	0	20	L	30	Х	2019	L	2031	А				
				31	Z	2020	М	2032	В				
						2021	Ν	and	so on				

 Table 2: Production date code.

Example of how to decode production location and date code:

Location:	С		\rightarrow	Wuxi
Day:	Т		\rightarrow	26 th
Year:	F		\rightarrow	2015
Month:		6	\rightarrow	June

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s	
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s	
<i>T</i> > 220 °C	30 s to 70 s	
<i>T</i> > 230 °C	min. 10 s	
<i>T</i> > 245 °C	max. 20 s	
<i>T</i> ≥ 255 °C	-	
peak temperature T_{peak}	250 °C +0/-5 °C	
wetting temperature T _{min}	230 °C +5/-0 °C for 10 s ± 1 s	
cooling rate	≤ 3 K/s	
soldering temperature T	measured at solder pads	

 Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

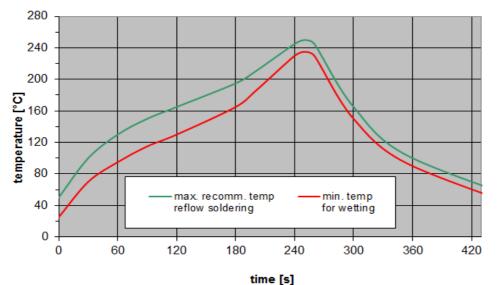


Figure 12: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

13.3 Shelf life

The shelf life of components is determined by solderability of the package terminals. It is specified as 2 years from manufacturing date assuming the following conditions:

- storage in original packaging and non-aggressive atmosphere,
- storage temperature ranging from −25 °C to +40 °C, and
- storage humidity with ≤ 75 % r.h. mean annual humidity, ≤ 95 % r.h. for max. 30 days / year, and no dew condensation.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

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14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

15 Important notes

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